



## Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE92464ED	Issued	08. April 2022
MA#	MA005423729		
Package	PG-DSO-36-72	Weight*	539.31 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.051	1.12	1.12	11220	11220
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		447	
	non noble metal	copper	7440-50-8	240.973	44.68	44.73	446817	447398
wire	non noble metal	copper	7440-50-8	3.150	0.58	0.58	5841	5841
encapsulation	organic material	carbon black	1333-86-4	0.830	0.15		1540	
	plastics	epoxy resin	-	32.385	6.00		60048	
	inorganic material	silicondioxide	60676-86-0	243.576	45.19	51.34	451643	513231
leadfinish	non noble metal	tin	7440-31-5	6.656	1.23	1.23	12341	12341
plating	noble metal	silver	7440-22-4	3.599	0.67	0.67	6673	6673
glue	plastics	epoxy resin	-	0.311	0.06		577	
	noble metal	silver	7440-22-4	1.467	0.27	0.33	2719	3296
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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